

ABSTRACT

This invention is directed to apparatus and a method for removing particles from a surface, such as a semiconductor wafer. A fluid is applied to the surface on which the particles are distributed so as to coat the particles with the fluid. At least some of these particles have a dimension of less than approximately one micron. A suction force is applied in the vicinity of the surface after applying the fluid so as to remove from the surface the majority of those particles having the dimension of less than approximately one micron.